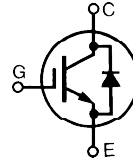


High Voltage, High Gain BIMOSFET™ Monolithic Bipolar MOS Transistor

IXBH20N300 IXBT20N300

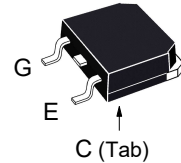


$$\begin{aligned} V_{CES} &= 3000V \\ I_{C110} &= 20A \\ V_{CE(sat)} &\leq 3.2V \end{aligned}$$

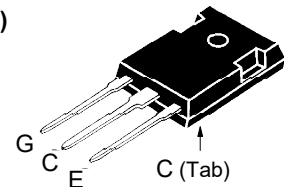
Symbol	Test Conditions	Maximum Ratings	
V_{CES}	$T_C = 25^\circ\text{C}$ to 150°C	3000	V
V_{CGR}	$T_J = 25^\circ\text{C}$ to 150°C , $R_{GE} = 1M\Omega$	3000	V
V_{GES}	Continuous	± 20	V
V_{GEM}	Transient	± 30	V
I_{C25}	$T_C = 25^\circ\text{C}$	50	A
I_{C110}	$T_C = 110^\circ\text{C}$	20	A
I_{CM}	$T_C = 25^\circ\text{C}$, 1ms	140	A
SSOA (RBSOA)	$V_{GE} = 15V$, $T_{VJ} = 125^\circ\text{C}$, $R_G = 20\Omega$ Clamped Inductive Load	$I_{CM} = 130$ 1500	A V
P_C	$T_C = 25^\circ\text{C}$	250	W
T_J		-55 ... +150	$^\circ\text{C}$
T_{JM}		150	$^\circ\text{C}$
T_{stg}		-55 ... +150	$^\circ\text{C}$
T_L	Maximum Lead Temperature for Soldering	300	$^\circ\text{C}$
T_{SOLD}	Plastic Body for 10 seconds	260	$^\circ\text{C}$
M_d	Mounting Torque (TO-247)	1.13/10	Nm/lb.in.
Weight	TO-268	4	g
	TO-247	6	g

Symbol	Test Conditions ($T_J = 25^\circ\text{C}$ Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
BV_{CES}	$I_C = 250\mu\text{A}$, $V_{GE} = 0V$	3000		V
$V_{GE(th)}$	$I_C = 250\mu\text{A}$, $V_{CE} = V_{GE}$	2.5		5.0 V
I_{CES}	$V_{CE} = 0.8 \cdot V_{CES}$, $V_{GE} = 0V$ $T_J = 125^\circ\text{C}$			35 μA 1.5 mA
I_{GES}	$V_{CE} = 0V$, $V_{GE} = \pm 20V$			± 100 nA
$V_{CE(sat)}$	$I_C = 20A$, $V_{GE} = 15V$, Note 1 $T_J = 125^\circ\text{C}$		2.7 3.2	V V

TO-268
(IXBT)



TO-247
(IXBH)



G = Gate C = Collector
E = Emitter Tab = Collector

Features

- High Blocking Voltage
- Anti-Parallel Diode
- International Standard Packages
- Low Conduction Losses

Advantages

- Low Gate Drive Requirement
- High Power Density

Applications:

- Switch-Mode and Resonant-Mode Power Supplies
- Uninterruptible Power Supplies (UPS)
- Laser Generators
- Capacitor Discharge Circuits
- AC Switches

Symbol Test Conditions

(T_J = 25°C Unless Otherwise Specified)

Characteristic Values

		Min.	Typ.	Max.
g_{fs}	I _C = 20A, V _{CE} = 10V, Note 1	11	18	S
C_{ies}	V _{CE} = 25V, V _{GE} = 0V, f = 1MHz		2230	pF
C_{oes}			92	pF
C_{res}			33	pF
Q_g	I _C = 20A, V _{GE} = 15V, V _{CE} = 1000V		105	nC
Q_{ge}			13	nC
Q_{gc}			45	nC
t_{d(on)}	Resistive Switching Times, T_J = 25°C I _C = 20A, V _{GE} = 15V V _{CE} = 1250V, R _G = 10Ω		64	ns
t_r			210	ns
t_{d(off)}			300	ns
t_f			504	ns
t_{d(on)}	Resistive Switching Times, T_J = 125°C I _C = 20A, V _{GE} = 15V V _{CE} = 1250V, R _G = 10Ω		68	ns
t_r			540	ns
t_{d(off)}			300	ns
t_f			395	ns
R_{thJC}	(TO-247)		0.21	0.50 °C/W
R_{thCS}				°C/W

Reverse Diode

Symbol Test Conditions

(T_J = 25°C Unless Otherwise Specified)

Characteristic Values

		Min.	Typ.	Max.
V_F	I _F = 20A, V _{GE} = 0V			2.1 V
t_{rr}	I _F = 10A, V _{GE} = 0V, -di _F /dt = 100A/μs		1.35	μs
I_{RM}			30	A

Note 1: Pulse test, t ≤ 300μs, duty cycle, d ≤ 2%.

Littelfuse reserves the right to change limits, test conditions and dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents:

4,835,592	4,931,844	5,049,961	5,237,481	6,162,665	6,404,065 B1	6,683,344	6,727,585	7,005,734 B2	7,157,338B2
4,860,072	5,017,508	5,063,307	5,381,025	6,259,123 B1	6,534,343	6,710,405 B2	6,759,692	7,063,975 B2	
4,881,106	5,034,796	5,187,117	5,486,715	6,306,728 B1	6,583,505	6,710,463	6,771,478 B2	7,071,537	

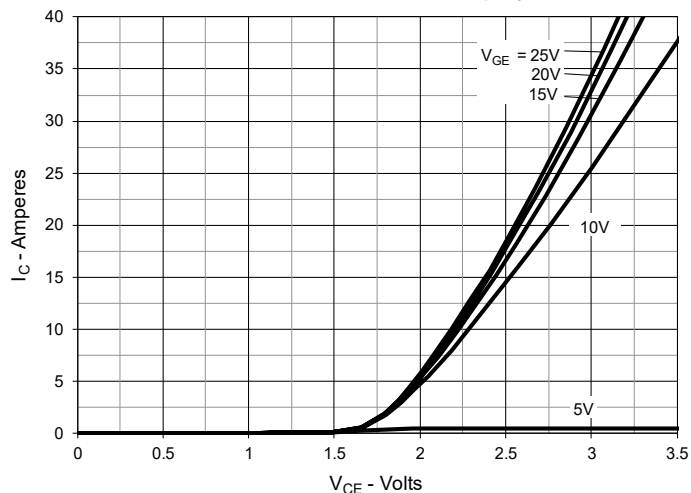
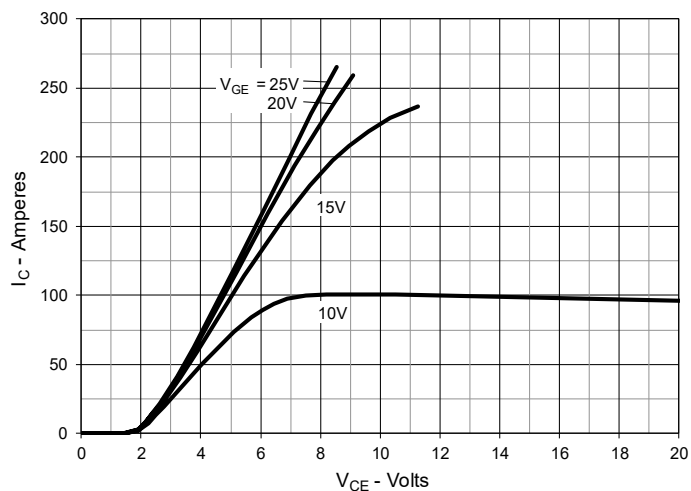
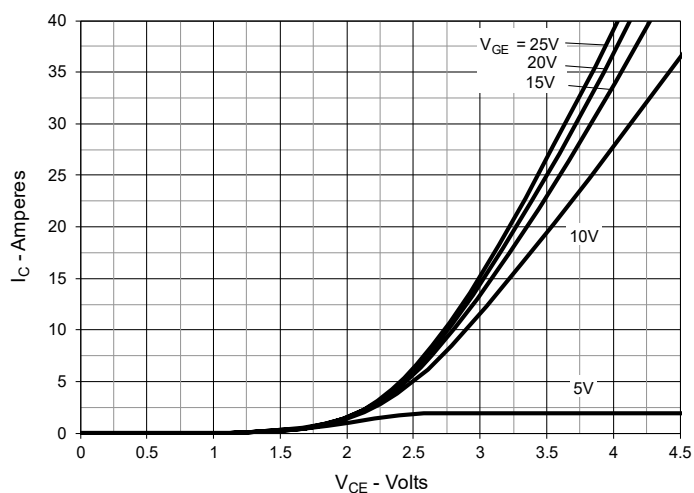
Fig. 1. Output Characteristics @ $T_J = 25^\circ\text{C}$ Fig. 2. Extended Output Characteristics @ $T_J = 25^\circ\text{C}$ Fig. 3. Output Characteristics @ $T_J = 125^\circ\text{C}$ 

Fig. 4. Dependence of VCE(sat) on Junction Temperature

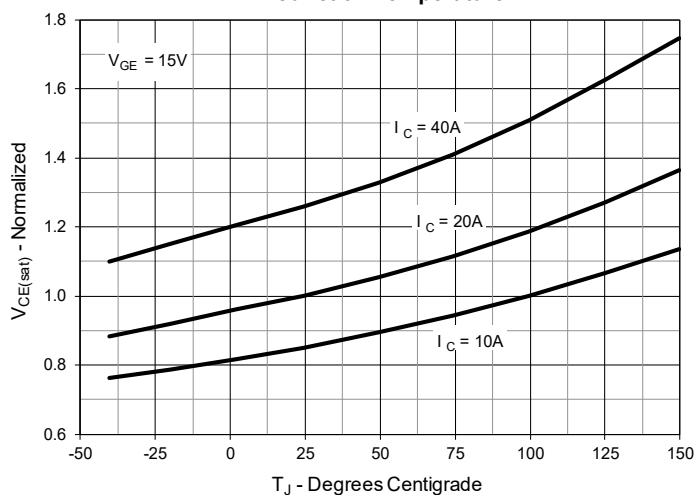


Fig. 5. Collector-to-Emitter Voltage vs. Gate-to-Emitter Voltage

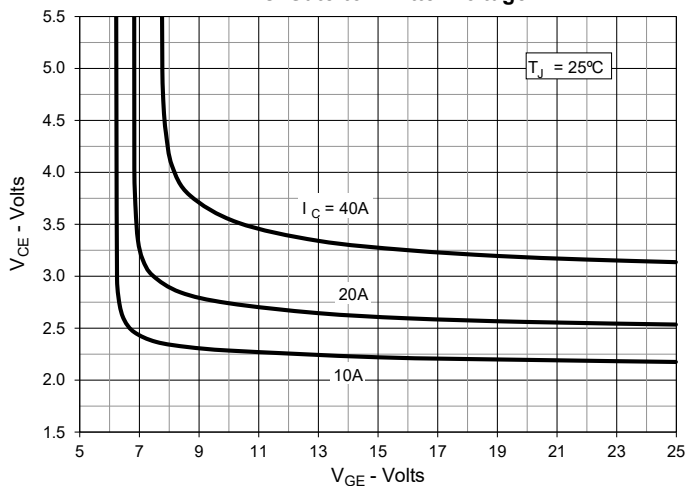


Fig. 6. Input Admittance

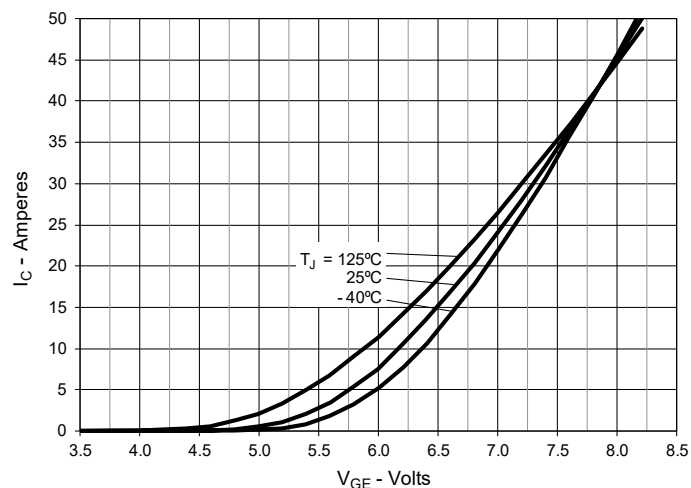


Fig. 7. Transconductance

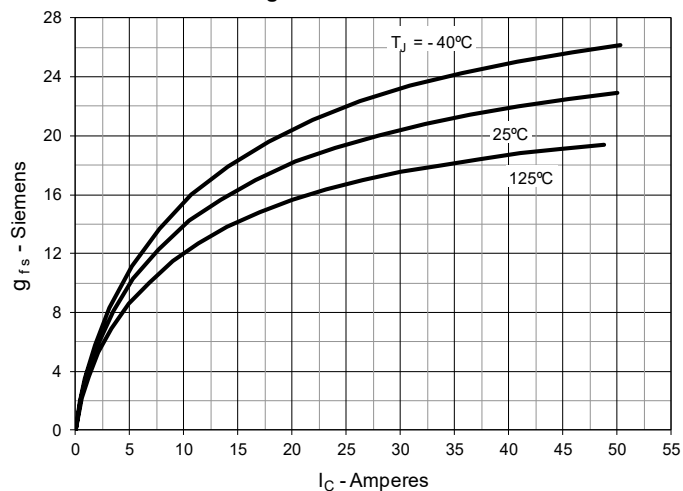


Fig. 8. Forward Voltage Drop of Intrinsic Diode

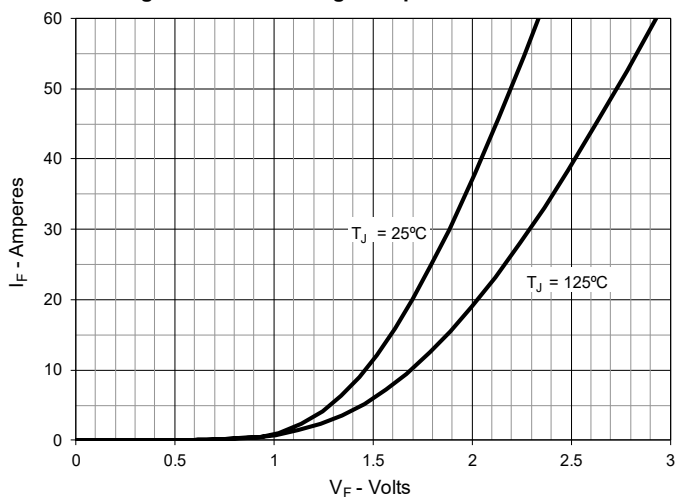


Fig. 9. Gate Charge

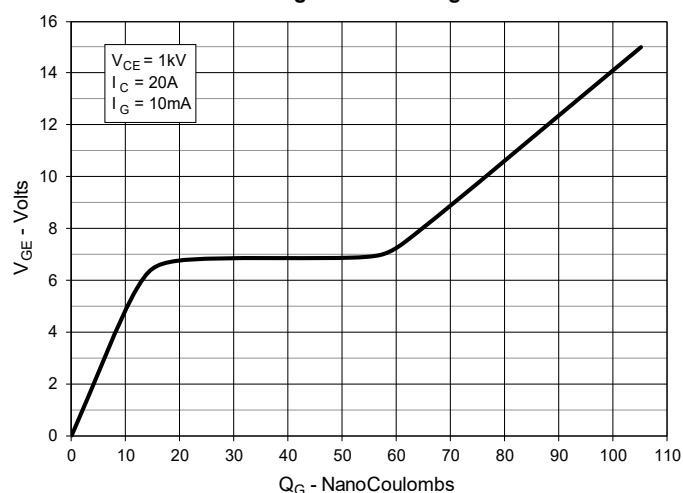


Fig. 10. Capacitance

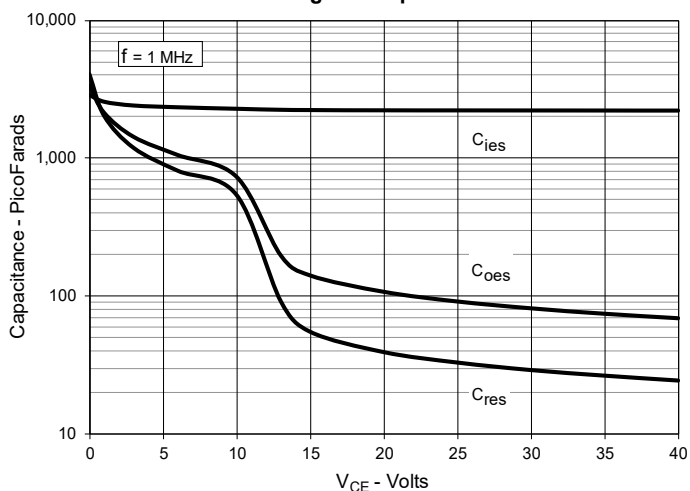


Fig. 11. Reverse-Bias Safe Operating Area

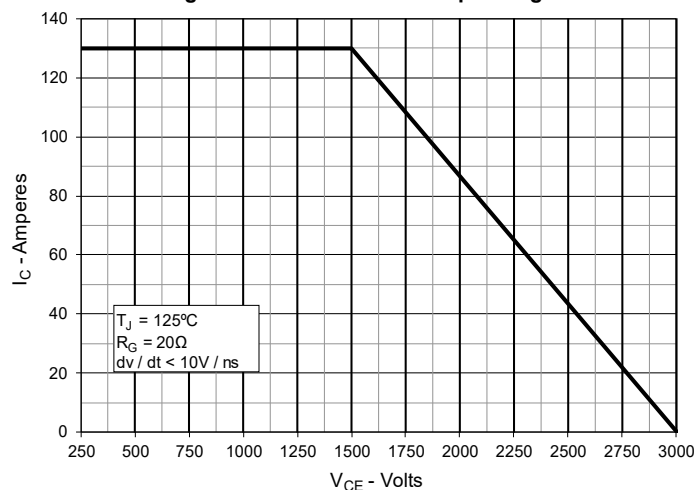


Fig. 12. Maximum Transient Thermal Impedance

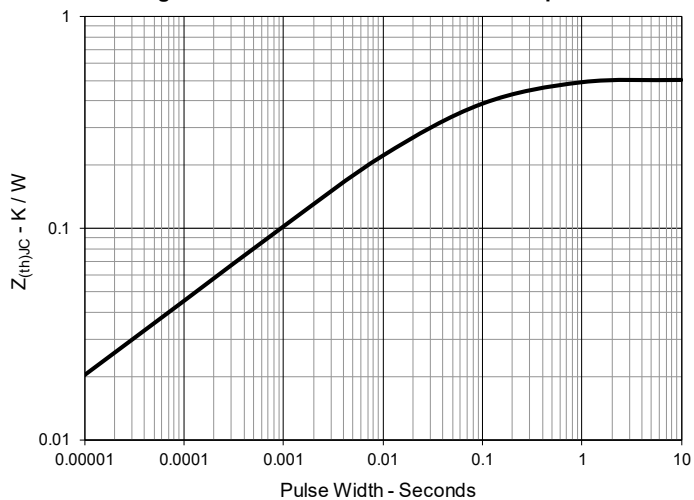


Fig. 13. Resistive Turn-on Rise Time vs. Junction Temperature

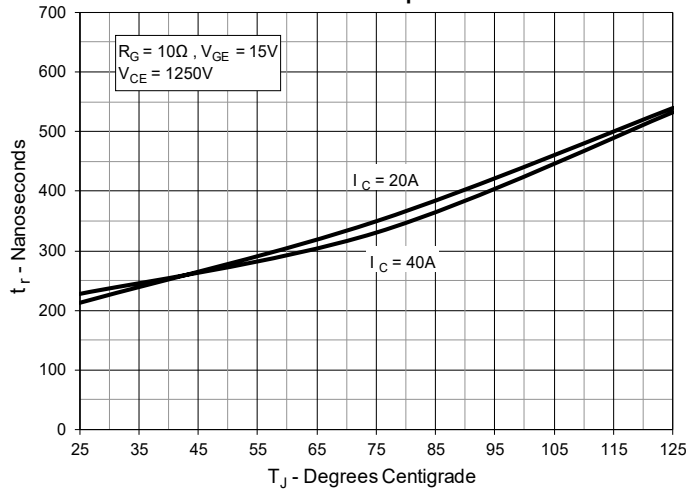


Fig. 14. Resistive Turn-on Rise Time vs. Collector Current

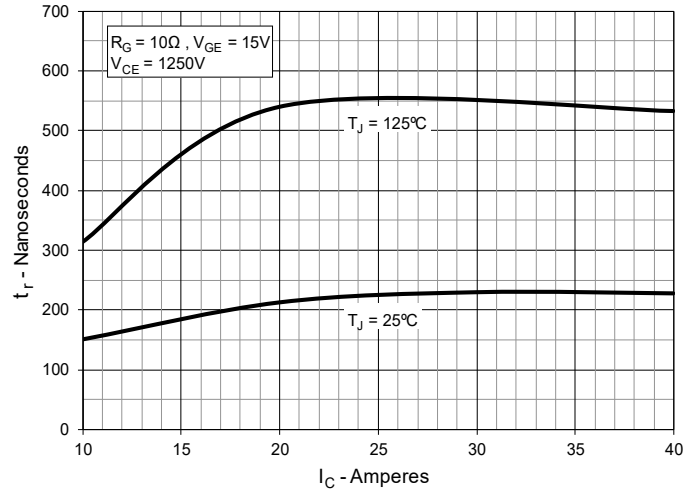


Fig. 15. Resistive Turn-on Switching Times vs. Gate Resistance

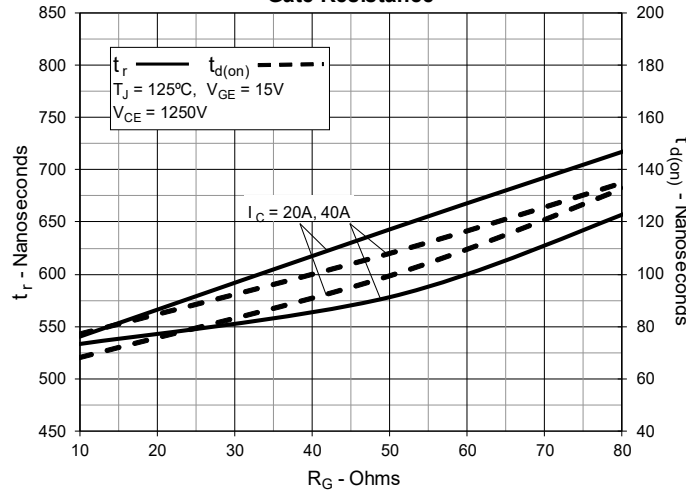


Fig. 16. Resistive Turn-off Switching Times vs. Junction Temperature

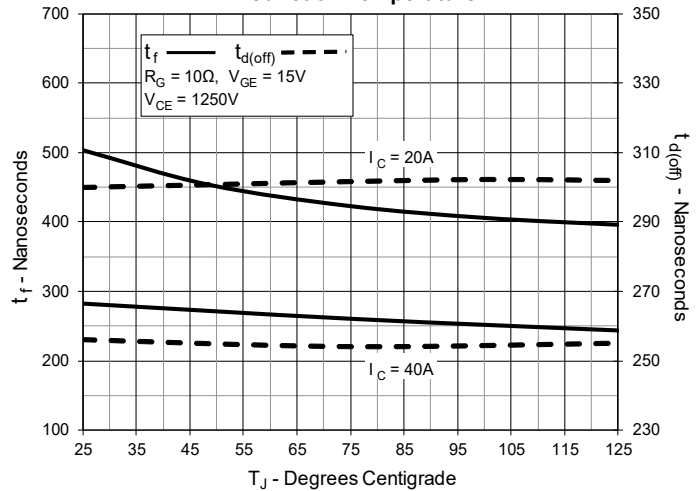


Fig. 17. Resistive Turn-off Switching Times vs. Collector Current

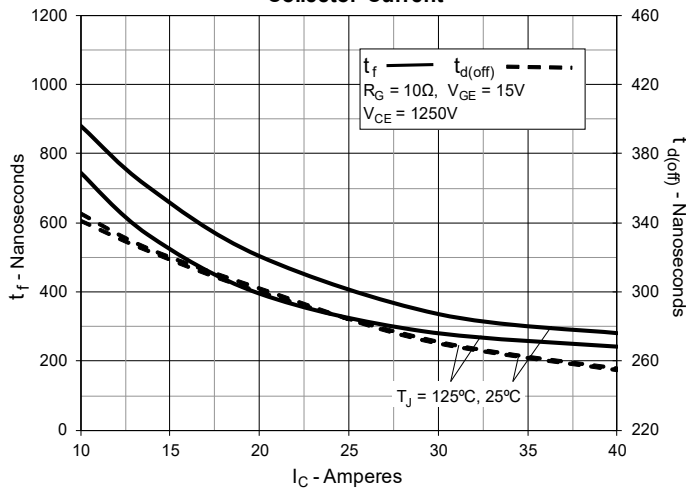
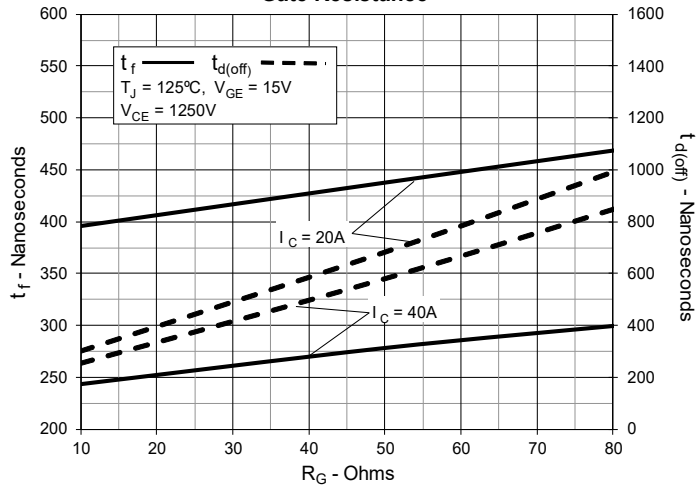
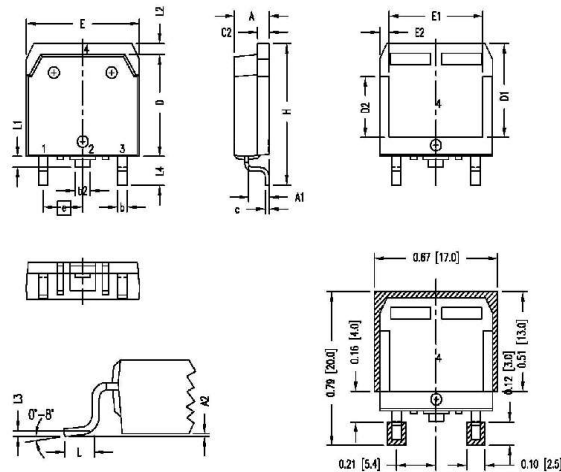


Fig. 18. Resistive Turn-off Switching Times vs. Gate Resistance



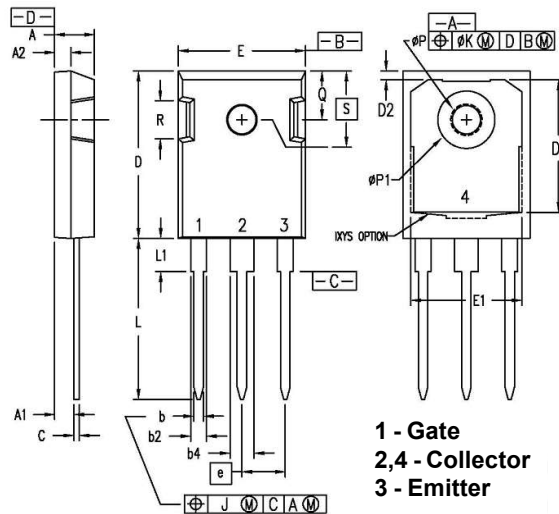
TO-268 Outline



1 - Gate
2,4 - Collect
3 - Emitter

SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.193	.201	4.90	5.10
A1	.106	.114	2.70	2.90
A2	.001	.010	0.02	0.25
b	.045	.057	1.15	1.45
b2	.075	.083	1.90	2.10
C	.016	.026	0.40	0.65
C2	.057	.063	1.45	1.60
D	.543	.551	13.80	14.00
D1	.488	.500	12.40	12.70
D2	.320	.335	8.13	8.50
E	.624	.632	15.85	16.05
E1	.524	.535	13.30	13.60
E2	.045	.055	1.14	1.39
e	.215 BSC		5.45 BSC	
H	.736	.752	18.70	19.10
L	.094	.106	2.40	2.70
L1	.047	.055	1.20	1.40
L2	.039	.045	1.00	1.15
L3	.010 BSC		0.25 BSC	
L4	.150	.161	3.80	4.10

TO-247 Outline



1 - Gate
2,4 - Collector
3 - Emitter

SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.190	.205	4.83	5.21
A1	.090	.100	2.29	2.54
A2	.075	.085	1.91	2.16
b	.045	.055	1.14	1.40
b2	.075	.087	1.91	2.20
b4	.115	.126	2.92	3.20
C	.024	.031	0.61	0.80
D	.819	.840	20.80	21.34
D1	.650	.690	16.51	17.53
D2	.035	.050	0.89	1.27
E	.620	.635	15.75	16.13
E1	.545	.565	13.84	14.35
e	.215 BSC		5.45 BSC	
J	---	.010	---	0.25
K	---	.025	---	0.64
L	.780	.810	19.81	20.57
L1	.150	.170	3.81	4.32
øP	.140	.144	3.55	3.65
øP1	.275	.290	6.99	7.37
Q	.220	.244	5.59	6.20
R	.170	.190	4.32	4.83
S	.242 BSC		6.15 BSC	